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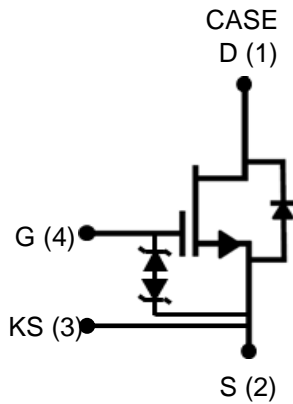
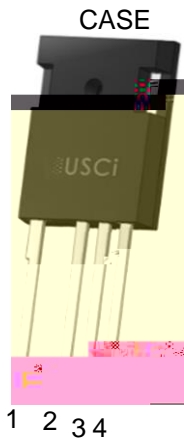


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DATASHEET

UF3C065040K4S



Part Number	Package	Marking
UF3C065040K4S	TO-247-4L	UF3C065040K4S



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Rev. , January % 0 ‡ % 0 OE

Description

United Silicon Carbide's cascode products co-package its high-performance F3 SiC fast JFETs with a cascode optimized MOSFET to produce the only standard gate drive SiC device in the market today. This series exhibits very fast switching using a 4-terminal TO-247 package and the best reverse recovery characteristics of any device of similar ratings. These devices are excellent for switching inductive loads, and any application requiring standard gate drive.

Features

- Š Typical on-resistance $R_{DS(on),typ}$ of 42m
- Š

Typical applications

- Š EV charging
- Š PV inverters
- Š Switch mode power supplies
- Š Power factor correction modules
- Š Motor drives
- Š Induction heating



Maximum Ratings

	Symbol		Value	Units	
Gate-source voltage	V_{DS}		650	V	
	V_{GS}	DC	-25 to +25	V	
			54	A	
			40	A	
		I_{DM}		125	A
		E_{AS}		76	mJ
Max. lead temperature for soldering,	P_{tot}		326	W	
	$T_{J,max}$		175	°C	
	T_J, T_{STG}		-55 to 175	°C	
	T_L		250	°C	

1. Limited by $T_{J,max}$
2. Pulse width t_p limited by $T_{J,max}$
3. Starting $T_J = 25^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Test Conditions	Value		Units
			Min	Typ	
Thermal resistance, junction-to-case	R_T		0.35	0.46	°C/W



Electrical Characteristics ($T_J = +25^\circ\text{C}$ unless otherwise specified)

Typical Performance - Static

		Min	Typ	Max	
	BV_{DS}	650			V
			0.7	150	
			10		
	I_{GSS}		6	20	FA
			42	52	
Drain-source on-resistance			78		
	$V_{G(th)}$	4	5	6	V
	R_G		4.5		:

Typical Performance - Reverse Diode

		Min	Typ	Max	
	I_S			54	A
	$I_{S,pulse}$			125	A
			1.5	1.75	
			1.8		
Reverse recovery charge	Q_{rr}		$V_R=400V, I_F=40A,$ $V_{GS}=-5V, R_{G_EXT}=20 \Omega,$	138	nC
Reverse recovery time	t_{rr}		$di/dt=1100A/\mu s,$ $T_J=25^\circ\text{C}$	38	ns
Reverse recovery charge	Q_{rr}		$V_R=400V, I_F=40A,$ $V_{GS}=-5V, R_{G_EXT}=20 \Omega,$	137	nC
Reverse recovery time	t_{rr}		$di/dt=1100A/\mu s,$ $T_J=150^\circ\text{C}$	38	ns



Typical Performance - Dynamic

Min

Typ

Max



Typical Performance Diagrams

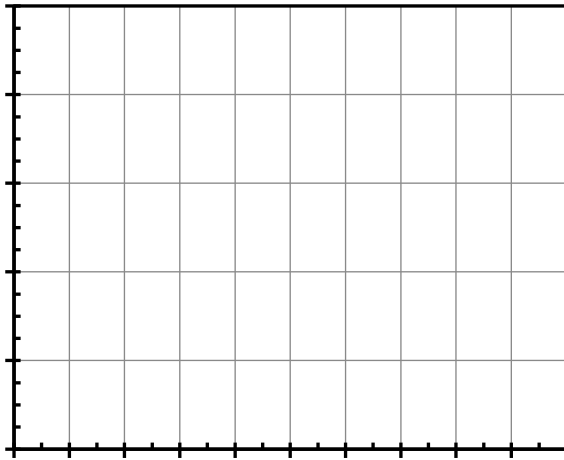


Figure 1. Typical output characteristics at $T_J = -55^\circ\text{C}$, $t_p < 250 \text{ ns}$

Figure 2. Typical output characteristics at $T_J = 25^\circ\text{C}$, $t_p < 250 \text{ ns}$

Figure 3. Typical output characteristics at $T_J = 175^\circ\text{C}$, $t_p < 250 \text{ ns}$

Figure 4. Normalized on-resistance vs. temperature at $V_{GS} = 12\text{V}$ and $I_D = 40\text{A}$

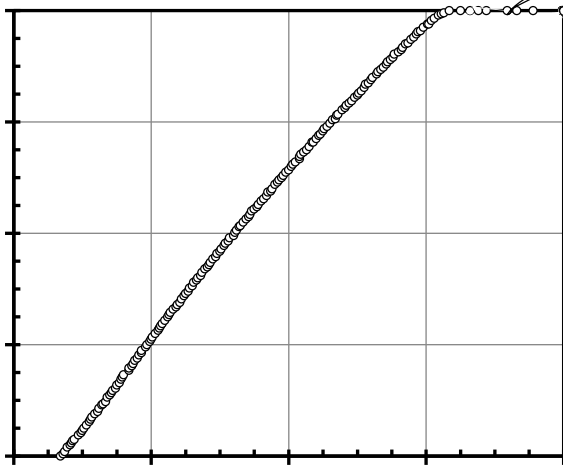


Figure 9. 3rd quadrant characteristics at $T_j = -55^\circ\text{C}$

Figure 10. 3rd quadrant characteristics at $T_j = 25^\circ\text{C}$

Figure 11. 3rd quadrant characteristics at $T_j = 175^\circ\text{C}$

Figure 12. Typical stored energy in C_{OSS} at $V_{GS} = 0\text{V}$



Figure 13. Typical capacitances at $f = 100\text{kHz}$ and $V_{GS} = 0\text{V}$

Figure 14. DC drain current derating



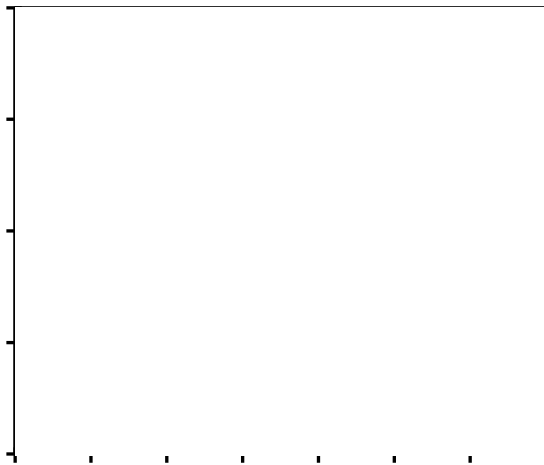


Figure 21. Clamped inductive switching energy vs. junction temperature at $V_{DS} = 400V$ and $I_D = 40A$

Figure 22. Reverse recovery charge Q_{rr} vs. junction temperature

Applications Information

SiC cascodes are enhancement-mode power switches formed by a high-voltage SiC depletion-mode JFET and a low-voltage silicon MOSFET connected in series. The silicon MOSFET serves as the control unit while the SiC JFET provides high voltage blocking in the off state. This combination of devices in a single package provides compatibility with standard gate drivers and offers superior performance in terms of low on-resistance ($R_{DS(on)}$), output capacitance (C_{oss}), gate charge (Q_g), and reverse recovery charge (Q_{rr}) leading to low conduction and switching losses. The SiC cascodes also provide excellent reverse conduction capability eliminating the need for an external anti-parallel diode.

Like other high performance power switches, proper PCB layout design to minimize circuit parasitics is strongly recommended due to the high dv/dt and di/dt rates. An external gate resistor is recommended when the cascode is working in the diode mode in order to achieve the optimum reverse recovery performance. For more information on cascode operation, see www.unitedsic.com.

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PART MARKING

TO-247-4L PACKAGE
OUTLINE, PART MARKING
AND TUBE SPECIFICATIONS

PACKING TYPE

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